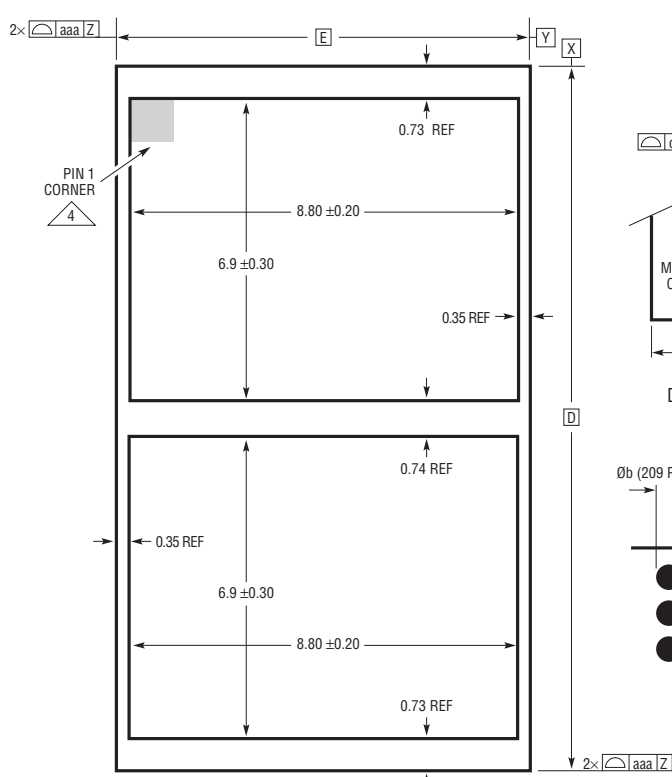
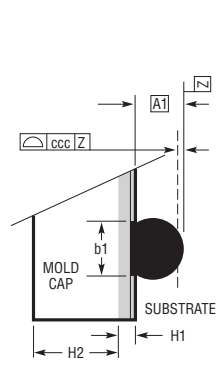


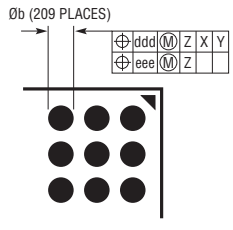
BGA Package
209-Lead (16mm × 9.50mm × 11.22mm)
 (Reference LTC DWG# 05-08-7001 Rev C)



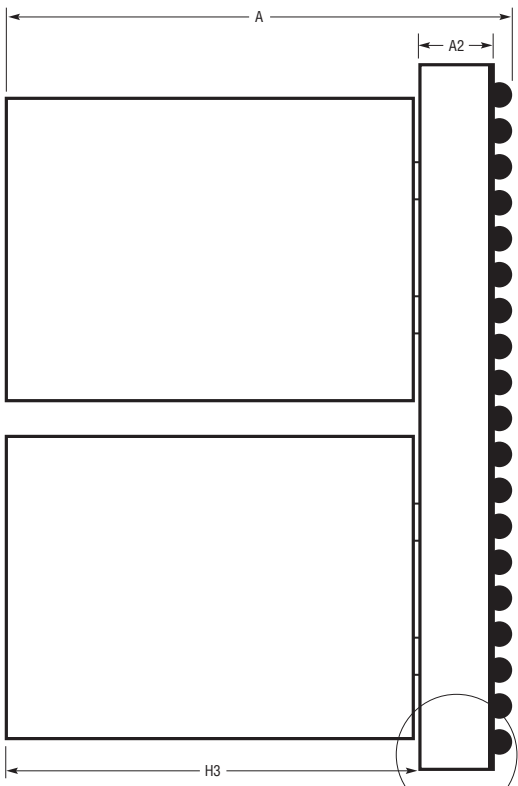
PACKAGE TOP VIEW



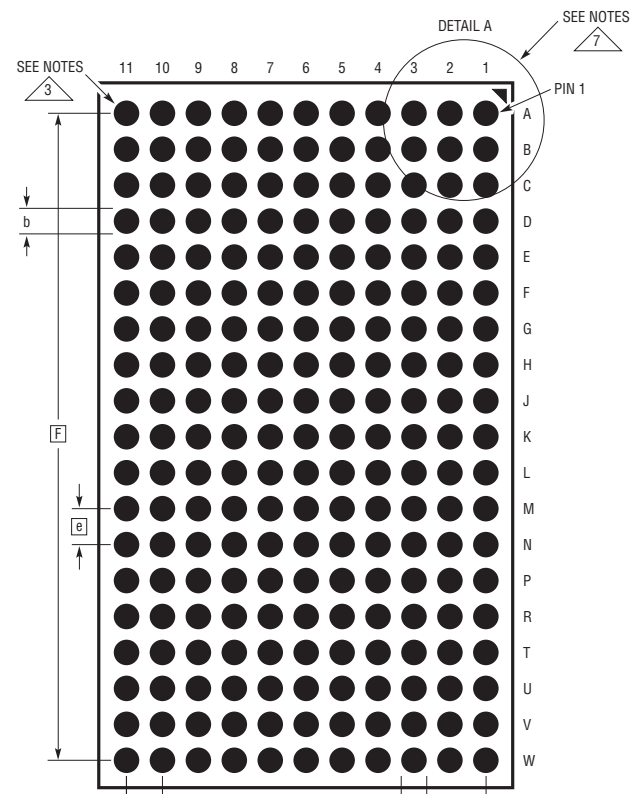
DETAIL B



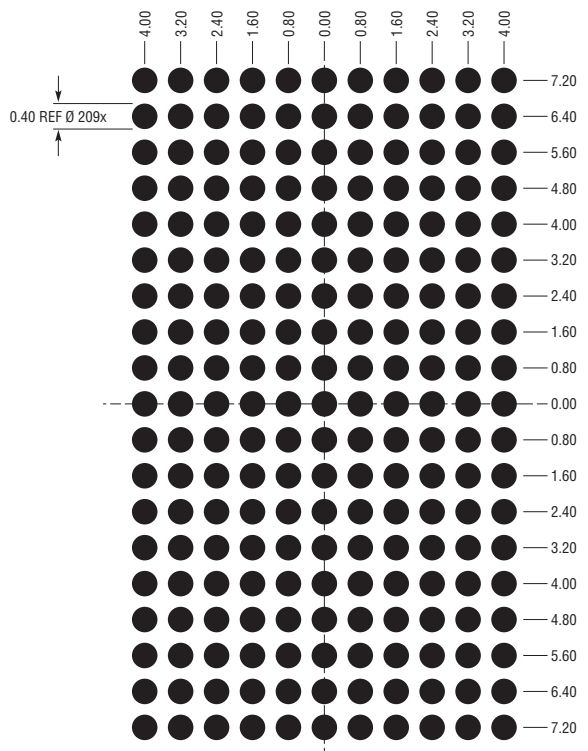
DETAIL A



DETAIL B PACKAGE SIDE VIEW



PACKAGE BOTTOM VIEW

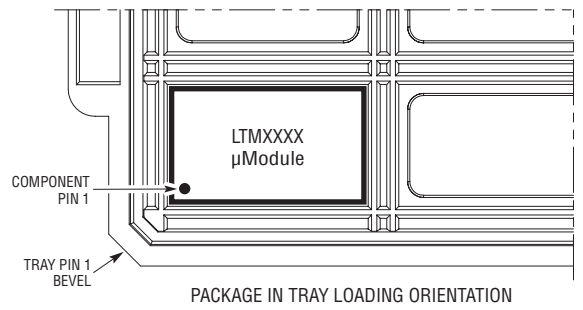


SUGGESTED PCB LAYOUT TOP VIEW

DIMENSIONS				
SYMBOL	MIN	NOM	MAX	NOTES
A	10.82	11.22	11.62	
A1	0.30	0.40	0.50	BALL HT
A2	1.72	1.82	1.92	
b	0.45	0.50	0.55	BALL DIMENSION
b1	0.37	0.40	0.43	PAD DIMENSION
D		16.00		
E		9.50		
e		0.80		
F		14.40		
G		8.00		
H1		0.32 REF		SUBSTRATE THK
H2		1.50 REF		MOLD CAP HT
H3	8.80	9.00	9.20	INDUCTOR HT
aaa			0.15	
ccc			0.20	
ddd			0.15	
eee			0.08	

TOTAL NUMBER OF BALLS: 209

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
 2. ALL DIMENSIONS ARE IN MILLIMETERS
 - 3 BALL DESIGNATION PER JEP95
 - 4 DETAILS OF PIN 1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN 1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
 5. PRIMARY DATUM -Z- IS SEATING PLANE
 - 6 PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG μModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION